

HL2002-750,850

750-nm Cut 850-nm Cut LED Casting resin System

1.0 Description

HL2002-750,850 is a 750nm Cut,850nm Cut LED epoxy casting compound developed specifically for the encapsulation of optoelectronic display, lams and chip LED. This low viscosity, long pot life system offers exceptional optical clarify and good thermal shock characteristics.

2.0 Specification of product

	Part A	Part B	Test method
Color	Black	Clear	Visual
Specific gravity at 25°C	1.2	1.2	Density Cup
Viscosity at 25°C , cps Brookfield RVF,	3000	130	BH Type Viscometer
Shelf life at 25°C, months	12	9	

3.0 Typical cured characteristics

Values are not intended for use in the preparation of specifications.

All measurements taken at 25°C unless otherwise noted.

3.1 Physical

	HL2002-750,850	Test method
Color	Black	Visual
Hardness	89	Shore D
Flex strength(kg/mm ²)	16.1	JIS-K-6911
Flex modulus(kg/mm ²)	338	JIS-K-6911
Moisture absorption, % 100C/1h	0.41	Boil
Glass transition temp., °C	130	TMA
Coefficient of thermal expansion CTE1(ppm/°C) CTE2(ppm/°C)	70 180	TMA

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4. Handling

HL2002-750,-850(A)/ HL2002(B)

Mix ratio, parts by weight*	100/95
Pot life at 25°C, 200gr. mass, hrs.	7
Mixed viscosity at 25°C, CPS, Spindle 2, Speed 10	600
Gel time at 121°C, min.	6

Parts may be demolded after gelation.

*The mix ratio of HL2002-750 is fixed by its chemistry. Any attempt to speed up or slow the cure by adding more or less hardener will result in degraded material. To aid deairing, combine HL2002-750(A) & HL2002-750(B), warm to 40-50°C for 20 min. and deair. Cool to room temperature for use.

5. Caution:

HL2002750(A)&(B) may cause skin irritation. Avoid skin contact. If contact occurs, wash skin with soap and water at the first opportunity.

6 Cure Schedule

Recommended cure 135°C/1hr+150°C/4hrs

Some variations in listed values may occur; customer should determine whether cure other than recommended above will give satisfactory results.

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